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NI PXIe-6555/6556 Specifications

200 MHz Digital Waveform Generator/Analyzer with PPMU

このドキュメントには、日本語ページも含まれています。

This document provides the specifications for the NI PXIe-6555 (NI 6555) and the NI PXIe-6556 (NI 6556). Specifications are subject to change without notice. For the most recent NI 6555/6556 specifications, visit ni.com/manuals. To access the NI 6555/6556 documentation, including the *NI Digital Waveform Generator/Analyzer Getting Started Guide*, which contains functional descriptions of the NI 6555/6556 signals and the connector pinouts, navigate to **Start»Programs»National Instruments»NI-HSDIO»Documentation**.



Caution The NI 6555/6556 has a maximum operating temperature range of 0 $^{\circ}$ C to +45 $^{\circ}$ C in all NI PXI Express and hybrid NI PXI Express chassis.



Hot Surface If the NI 6555/6556 has been in use, it might exceed safe handling temperatures and cause burns. Allow time to cool before removing the NI 6555/6556 from the chassis.



Caution Refer to the *Read Me First: Safety and Electromagnetic Compatibility* document for important safety and electromagnetic compatibility information. To obtain a copy of this document online, visit ni.com/manuals, and search for the document title.



Caution To ensure the specified EMC performance, operate this product only with shielded cables and accessories.



Caution To ensure specified EMC performance, you must install PXI EMC Filler Panels, National Instruments part number 778700-01, in all open chassis slots.



Caution To ensure the specified EMC performance, all I/O cables must be no longer than 3 m (10 ft).



Note All values were obtained using a 1 m cable (SHC68-C68-D4 recommended). Performance specifications are not guaranteed when using longer cables.



Terminology

Maximum and *minimum* specifications are warranted not to exceed these values within certain operating conditions and include the effects of temperature and uncertainty unless otherwise noted.

Typical specifications are unwarranted values that are representative of a majority (3σ) of units within certain operating conditions and include the effects of temperature and uncertainty unless otherwise noted.

Characteristic specifications are unwarranted values that are representative of an average unit operating at room temperature.

Nominal specifications are unwarranted values that are relevant to the use of the product and convey the expected performance of the product.

All specifications are *Typical* unless otherwise noted. These specifications are valid within the operating temperature range. Accuracy specifications are valid within ± 5 °C of self-calibration unless otherwise noted.

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Channel Specifications

Specification	Value	Comments
Number of data channels	24, per pin parametric measurement unit (PPMU) enabled	All data channels have pattern memory.
Direction control of data channels	Per channel	
Number of programmable function interface (PFI) channels	4 PPMU-enabled PFI channels: PFI 1, PFI 2, PFI 4/DDC CLK OUT, and PFI 5/STROBE 10 general PFI channels: PFI 0, PFI 3, and PFI <2431>	Refer to the <i>Waveform</i> <i>Specifications</i> section for more details.
Direction control of PFI channels	Per channel	
Number of clock terminals	4 input 2 output	Refer to the <i>Timing</i> <i>Specifications</i> section for more details.
Number of remote sense channels	28	All PPMU-enabled channels have remote sense capability.

Digital Generation Channels (DIO <0..23>, PFI 1, PFI 2, PFI 4, and PFI 5)



Specification	Va	Comments	
Generation signal type	Single-ended, ground refe	—	
Programmable generation voltage levels	Drive Voltage High Leve Drive Voltage Low Level Drive Tristate (V _{TT})	_	
Generation voltage range	-2 V to 6 V (default) or -2	V to 7 V	Software- selectable.
Generation voltage resolution	122 μV	_	
DC generation voltage accuracy	±5 °C of Self-Calibration	±15 °C of Self-Calibration	Maximum accuracy when
	±11 mV	±16 mV	operating within the specified self-calibration temperature range.
Generation voltage swing	400 mV to 8.0 V	Into a 1 M Ω load. Power limitations may restrict the number of channels toggling at full voltage swing.	
Output impedance	50 Ω		Nominal.

Specification	Value	Comments
Maximum allowed DC drive strength per channel	±35 mA	Nominal. Do <i>not</i> exceed the maximum power limit of the device.
Data channel tristate control	Per channel, per cycle	Software- selectable and hardware- timed.
Channel power-on state	Drivers disabled, high impedance	_
Output protection	The device can indefinitely sustain a short to any voltage between -3 V and 8.5 V provided that you observe the maximum drive strength limitations.	

Digital Acquisition Channels (DIO <0..23>, PFI 1, PFI 2, PFI 4, and PFI 5)



Specification	Value	Comments
Acquisition signal type	Single-ended, ground referenced	—
Programmable acquisition voltages	Compare Voltage High Threshold (V_{IH}) Compare Voltage Low Threshold (V_{IL}) Termination Voltage (V_{TT})	_
Acquisition voltage threshold range	-2 V to 7 V	
Acquisition and termination voltage resolution	122 μV	—
Termination voltage range	-2 V to 6 V (default) or -1 V to 7 V	—

Specification	Va	lue	Comments
DC acquisition voltage accuracy	±5 °C of Self-Calibration	Maximum accuracy when	
	$(V_{IL}) = \pm 25 \text{ mV}$ $(V_{IH}) = \pm 25 \text{ mV}$ $(V_{TT}) = \pm 11 \text{ mV}$	$(V_{IL}) = \pm 28 \text{ mV}$ $(V_{IH}) = \pm 28 \text{ mV}$ $(V_{TT}) = \pm 16 \text{ mV}$	operating within the specified self-calibration temperature range between -1.5 V and
Minimum detectable voltage swing	50 mV	6.8 V.	
Input impedance	High-impedance or 50Ω	Software- selectable.	
High impedance leakage	<5 nA	Characteristic.	
Input protection	The device can indefinite voltage between -3 V and observe the maximum dri		

Active Load Channels (Data <0..23> and PFI <1,2,4,5> Channels)



Note Active Loads are supported only for the NI 6556.

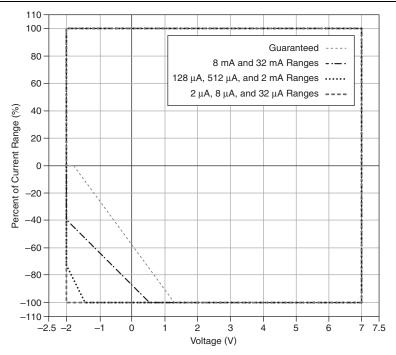
Specification		Comments		
Programmable levels	Commutating V Current Source Current Sink (I	_		
Load	Range	Resolution	Accuracy (±15 °C of Self-Calibration)	Typical accuracy with 3 V overdrive.
	1.5 mA to 24 mA	488 nA	±1 mA	

PPMU Channels (DIO <0..23>, PFI 1, PFI 2, PFI 4, and PFI 5)



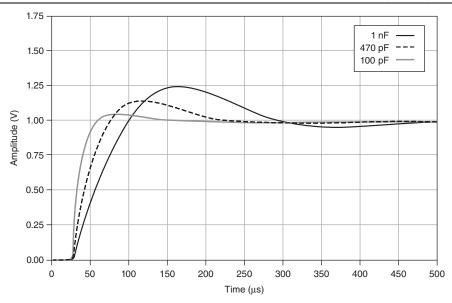
Specification	Value	Comments
PPMU signal type	Single-ended, ground referenced	Referenced to the ground pins on the VHDCI connector.
Programmable levels	Force voltage (F _V) Force current (F _I) Voltage clamp high (V _{CHI}) Voltage clamp low (V _{CLO})	Voltage clamps are only active when forcing current.

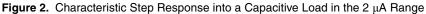




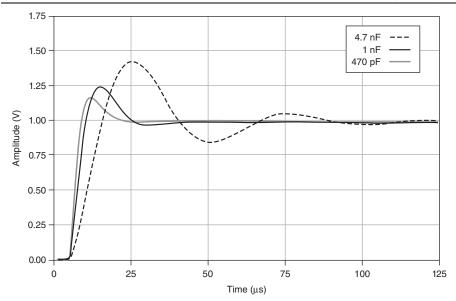
Specification	Value					Comments
Force voltage	Ranges	Resolution	Accuracy within ±5 °C of Self- Calibratio		Accuracy within ±15 °C of Self- Calibration	Maximum accuracy at the sense location.
	-2 V to 6 V (default) -1 V to 7 V	122 μV	±11	mV	±16 mV	
Force voltage	Cu	Irrent Range		Set	tling Time	Settled to
settling time		2 μΑ			150 µs	1% of the final value.
		8 μΑ			75 µs	1 V steps with 50% of
	32 µA, 128 µA, 512 µA			40 µs	the current	
	2 mA			45 µs	range load into 100 pF.	
		8 mA			55 µs	1
		32 mA			60 µs	
Load	Current Range			Ca	pacitance	These
capacitance		2 μΑ			1 nF	values represent
		8 μΑ			1 nF	the allowed load
	•		1 nF	capacitance		
					1 nF	through a 1 m SHC68-
		512 μΑ			4.7 nF	C68-D4
	2 mA			10 nF	cable to ensure a	
	8 mA				47 nF	well- behaved
		32 mA			100 nF	transient response.

Characteristic Step Response









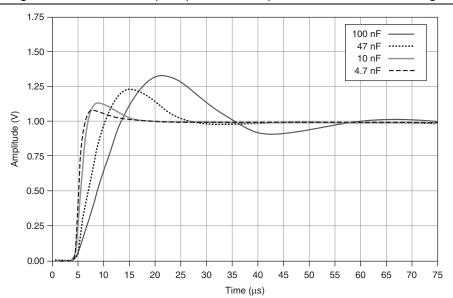
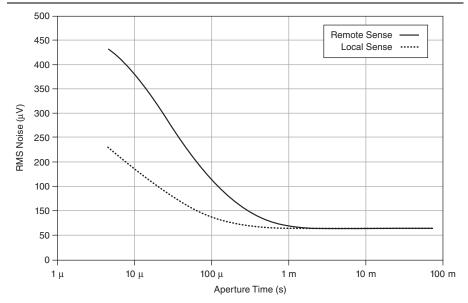
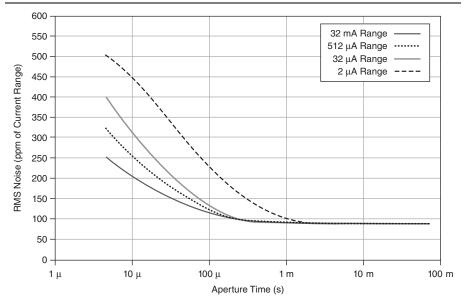


Figure 4. Characteristic Step Response into a Capacitive Load in the 32 mA Range

Specification	Value					Comments
Force current	Current Range Resolution			Nominal.		
resolution	±2 μA			60 pA		
	$\pm 8 \ \mu A$			240 pA		
		±32 μA			980 pA	
		±128 μA			3.9 nA	
		±512 μA			15.6 nA	
		±2 mA			60 nA	
		±8 mA			240 nA	
		±32 mA			980 nA	
Force current accuracy		±5 °C of	±5 °C of ±		uracy within ⊧15 °C of -Calibration	Maximum.
		1% of rang	e	1.3	3% of range	
Force current voltage clamps	Currer	nt Range	Reso	lution	Accuracy within ±15 °C of Self- Calibration	Maximum. Voltage clamps begin to conduct
	V _{CLO}	-2 V to 6 V	122	μV	±100 mV	within 700 mV of the programmable
	V _{CHI}	-1 V to 7 V				voltage level.
	Note: (V _{CHI} - V _{CL}	$_{\rm O}) > 1 { m V}$			
Aperture time range	4 μs to	4 µs to 65 ms				
Aperture time resolution	4 μs					—
Measure voltage	Accuracy within±15°C of Self- Range Resolution Calibration			Maximum accuracy at the sense location with one		
	-2 V to	7 V	228	μV	±3 mV	60 Hz PLC aperture.



Specification	Value	Value					
Measure	Current Range	Resolution	Nominal.				
current resolution	±2 µA	460 pA					
	±8 µA	1.8 nA					
	±32 μA	7.3 nA					
	±128 μA	30 nA					
	±512 μA	120 nA					
	±2 mA	460 nA					
	±8 mA	1.8 μΑ					
	±32 mA	7.3 μΑ					
Measure current accuracy	Accuracy within ±5 °C of Self-Calibration	Accuracy within ±15 °C of Self-Calibration	Maximum accuracy with one				
	1% of range	1.3% of range	60 Hz PLC aperture.				





Note I_{RMS} Noise is represented by the following equation:

 I_{RMS} Noise = (RMS Noise × Current Range) / 10⁶

For example, 100 ppm on a 32 mA range yields a noise of $3.2 \ \mu A$ RMS.

Specification	Value	Comments
I/O switch resistance	5.5 Ω	Nominal.
Remote feedback impedance	100 kΩ	Nominal.
Output protection	The device can indefinitely sustain a short to any voltage between -3 V and 8.5 V, provided that you observe the maximum drive strength limitations.	

General PFI Channels (PFI 0, PFI 3, and PFI <24..31>)

Specification	Value		Comments
Circuit type	PFI 0 and PFI 3: High-speed	I/O circuits	—
	PFI <2431>: 5 V compatib	le I/O circuits	
Generation voltage level	Low Voltage Levels, Characteristic High Voltage Levels, Characteristic		Nominal.
	0 V	3.3 V	
Drive	PFI 0 and PFI 3: ±33 mA	_	
strength	PFI <2431>: ±85 mA		
Output impedance	50 Ω		Nominal.
Output protection	The device can indefinitely sustain a short to any voltage between 0 V and 5 V.		_
Acquisition voltage level	Low Voltage High Voltage Thresholds Thresholds		Nominal.
	0.8 V	2 V	
Input protection	PFI 0 and PFI 3: -1 V to 5 V		Maximum.
	PFI <2431>: -1 V to 6.5 V		

EXTERNAL FORCE and EXTERNAL SENSE Channels

Note These specifications are valid for the EXTERNAL FORCE and EXTERNAL SENSE channels on the AUX I/O connector or on the REMOTE SENSE connector. The AUX I/O connector is available only on NI 6556 devices.

Specification	Value	Comments
Direction	EXTERNAL FORCE: input to the device EXTERNAL SENSE: output from the device	—
Analog bandwidth	EXTERNAL FORCE: 3 MHz EXTERNAL SENSE: 30 kHz	Characteristic with a single channel connected.
Range	-2 V to 7 V	—

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Specification	Value	Comments
Maximum current	±32 mA	Valid for EXTERNAL FORCE only.
Input protection	The device can indefinitely sustain a short to any voltage between -3 V and 8.5 V, provided that you observe the maximum drive strength limitations.	

CAL Channels

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Note These specifications are valid for the CAL channel on the AUX I/O connector and on the REMOTE SENSE connector. The AUX I/O connector is available only on NI 6556 devices.

Specification	Value	Comments
Direction	Output from the NI 6556 during external calibration. This channel is in a high-impedance or undriven state during normal operation.	
Voltage level	5 V	Nominal.
Drive strength	1 mA	Maximum allowed. Sourcing only.

Timing Specifications

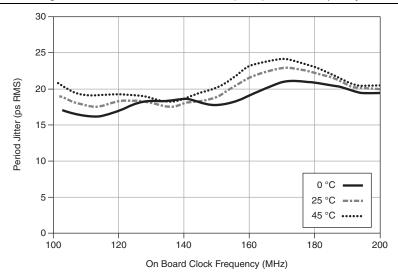
Sample Clock

Specification	Value	Comments
Sample clock sources	 Onboard Clock CLK IN (SMA jack connector) PXIe_DStarA (PXI Express backplane) STROBE (Digital Data & Control (DDC) connector; acquisition only) 	_
On Board Clock frequency range	800 Hz to 200 MHz	

Specification	Value	Comments
On Board Clock frequency resolution	<0.1 Hz	NI-HSDIO may be queried for the programmed frequency value.
On Board Clock frequency accuracy	±150 ppm	Nominal. Accuracy may be increased by using a higher performance external Reference clock.
CLK IN frequency range	20 kHz to 200 MHz	Refer to the <i>CLK</i> <i>IN (SMA Jack</i> <i>Connector)</i> section for restrictions based on waveform type.
PXIe_DStarA frequency range	800 Hz to 200 MHz	Refer to the <i>PXIe_DStarA</i> <i>(PXI Express</i> <i>Backplane)</i> section for more information.
STROBE frequency range	800 Hz to 200 MHz	Refer to the <i>PFI 5</i> as <i>STROBE (DDC</i> <i>Connector)</i> section for more information.
Sample clock relative delay adjustment range	±5 ns	To align multiple devices, apply a delay or phase
Sample clock relative delay adjustment resolution	3.125 ps	adjustment to the On Board Clock.
Exported Sample clock destinations	 DDC CLK OUT (DDC connector) CLK OUT (SMA jack connector) 	Internal Sample clocks with sources other than STROBE can be exported.

Specification	Va	lue	Comments
Exported Sample clock offset range (t _{CO})	0 ns to 2.4 ns		Software programmable.
Exported Sample clock offset resolution (t _{CO})	13 ps		
Exported Sample clock offset accuracy (t _{CO})	±200 ps		Software programmable.
Exported Sample	Minimum	Maximum	3.3 V at maximum
clock duty cycle (DDC CLK OUT)	42%	55%	clock rate (200 MHz). Not including the effects of system crosstalk.
Exported Sample clock period jitter	24 ps _{rms}		Characteristic; using On Board Clock.

Figure 7. Characteristic Period Jitter (RMS) versus Frequency



Generation Timing (Data, DDC CLK OUT, and PFI <0..3> Channels)

Specification	Value	Comments
Maximum data rate per channel	200 Mbps Supported for all logic families	—
Maximum data channel toggle rate	3.3 V swing: 100 MHz 5 V swing: 50 MHz	Toggle rates exceeding these values may invalidate CE certifications. Refer to the <i>Electromagnetic</i> <i>Compatibility</i> section for more information.

Figure 8 shows an eye diagram of a 200 Mbps pseudorandom bit sequence (PRBS) waveform at 3.3 V. This waveform was captured on a characteristic DIO channel at room temperature into high-impedance.

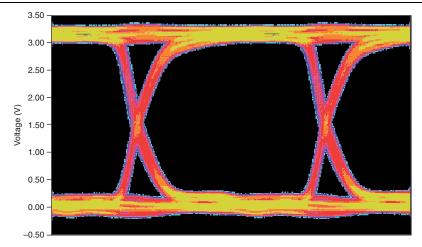
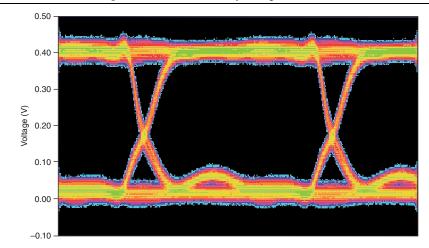
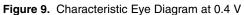


Figure 8. Characteristic Eye Diagram at 3.3 V

Figure 9 shows an eye diagram of a 200 Mbps PRBS waveform at 0.4 V. This waveform was captured on a characteristic DIO channel at room temperature into high-impedance.





Specification	Va	lue	Comments
Data channel-to-	NI 6555	NI 6556	There will be
channel skew	Maximum: 750 ps Characteristic: 300 ps	Maximum: 600 ps Characteristic: 300 ps	additional skew from crosstalk, acquisition threshold, and other transmission line effects in your system. You may see up to 150 ps of additional skew from differences between channels in the average rate of pattern transitions.
Data position	Sample clock rising e	dge	_
modes	Sample clock falling	edge	
	Delay from Sample c	lock rising edge	
Generation data	On Board Clock	External Clock	—
delay frequency	All supported frequencies	Frequencies ≥ 20 MHz	

Specification	Value	Comments	
Generation data delay range	-1 to 2 Sample clock cycles, expressed as a fraction of the Sample clock period	The sum of data delay and data deskew may	
Generation data deskew range	-2 to 3 Sample clock cycles, expressed as a time in seconds	not exceed -2 to 3 Sample clock cycles.	
Generation data delay and data deskew resolution	30 ps	Nominal.	

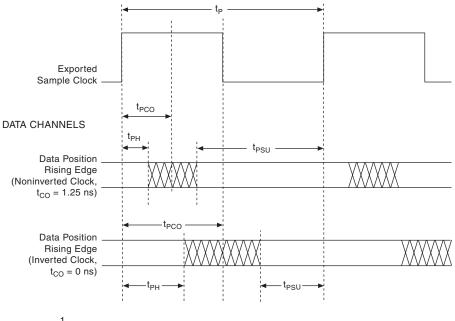
Generation Provided Setup and Hold Times

	Value			
Specification	NI 6555/65	56		
Provided Setup Time (t _{PSU})	t _p - t _{CO} - 850 ps			
Provided Hold Time (t _{PH})	t _{CO} - 700 ps	Characteristic		
Exported Sample Clock Offset (t _{CO}) is software programmable.				
Compare the setup and hold tim	es from the datasheet of your device	ce under test (DUT) to the		

Compare the setup and hold times from the datasheet of your device under test (DUT) to the values in the table above. The provided setup and hold times must be greater than the setup and hold times required for the DUT. If you require more setup time, configure your exported Sample clock mode to Inverted and/or delay your clock or data relative to the Sample clock.

Refer to Figure 10 for a diagram illustrating the relationship between the exported Sample clock mode and the provided setup and hold times.

Notes: This table assumes the data position is set to Sample clock rising edge and the noninverted Sample clock is exported to the DDC connector with t_{CO} programmed using exported Sample clock offset.



$$t_{P} = \frac{1}{f}$$
 = Period of Sample Clock
 t_{PH} = Provided Hold Time

t_{PSU} = Provided Setup Time

t_{PCO} = Time from Rising Clock Edge to Data Transition (Provided Clock to Out Time)

t_{CO} = Exported Sample Clock Offset



Note Provided setup and hold times account for maximum channel-to-channel skew and jitter.

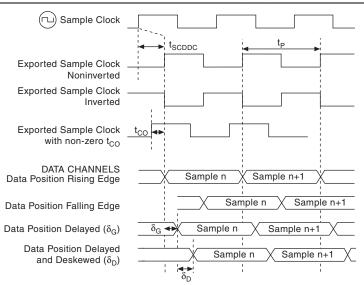


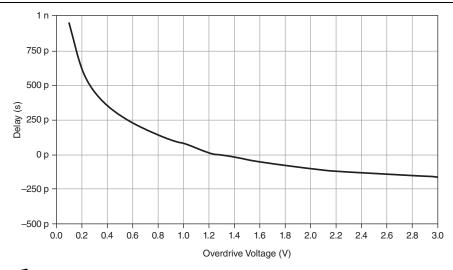
Figure 11. Generation Timing Diagram

$$\begin{split} t_{SCDDC} &: \text{Time Delay from Sample Clock (Internal) to DDC Connector} \\ -1 &\leq \delta_G \leq 2 : \text{Pattern Generation Channel Data Delay (Fraction of t_P)} \\ t_P &= \frac{1}{f} = \text{Period of Sample Clock} \\ t_{CO} &= \text{Exported Sample Clock Offset} \\ \delta_D &= \text{Pattern Generation Channel Deskew (Time)} \end{split}$$

Acquisition Timing (Data, STROBE, and PFI <0..3> Channels)

Specification	Va	lue	Comments
Maximum data rate per channel	200 Mbps		_
Channel-to-	NI 6555	NI 6556	There will be
channel skew	Maximum: 725 ps Characteristic: 300 ps	Maximum: 600 ps Characteristic: 300 ps	additional skew from crosstalk, acquisition threshold, overdrive, dispersion, and transmission line effects. You may see up to 175 ps of additional skew from differences between channels in the average rate of pattern transitions.

Figure 12. Typical Overdrive Dispersion Adjustment





Note Timing calibration executes with 1.25 V of overdrive.

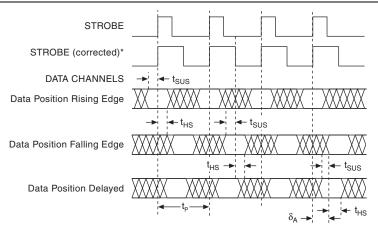
Specification	Value)	Comments
Data position modes	Sample clock rising edge	—	
	Sample clock falling edge	· .	
	Delay from Sample clock ri	sing edge	
Acquisition data	Onboard Clock	External Clock	—
delay and deskew frequency	All supported frequencies	Frequencies ≥ 20 MHz	
Acquisition data delay range	-1 to 2 Sample clock cycles of the Sample clock period.	expressed as a fraction	The sum of data delay and
Acquisition data deskew range	-2 to 3 Sample clock cycles expressed as a time in seconds.		data deskew may not exceed -2 to 3 Sample clock cycles.
Acquisition data delay and data deskew resolution	30 ps		

Setup and Hold Times to STROBE

Specification	Value			
Setup Time to STROBE (t _{SUS})				
	NI 6555	NI 6556		
f <20 MHz	2.18 ns	2.2 ns		
f≥20 MHz	1.82 ns	1.86 ns		
Hold Time to STROBE (t _{HS})				
	NI 6555	NI 6556		
f <20 MHz	3.18 ns	3.47 ns		
f≥20 MHz	1.41 ns	1.49 ns		

Includes maximum data channel-to-channel skew, but does not include system crosstalk. 1.65 V overdrive on all channels. Overall performance may vary with system crosstalk performance. NI 6556 values are specified within ± 15 °C of self-calibration.

Refer to Figure 13 for a diagram illustrating the relationship between the exported Sample clock mode and the setup and hold times to STROBE.



t_{SUS} = Set-Up Time to STROBE

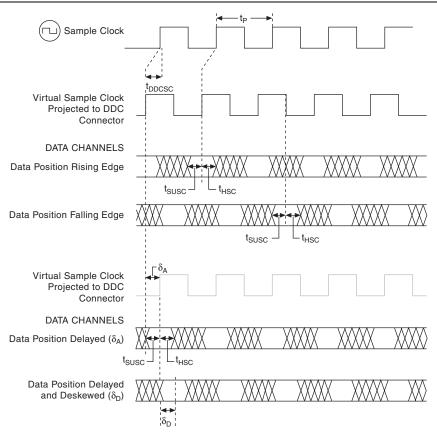
 t_{HS} = Hold Time from STROBE

-1 $\leq \delta_A \leq$ 2 : Acquisition Data Delay (fraction of t_P)

 $t_{P} = \frac{1}{f} =$ Sample Clock Period

*Note: When using an external Sample clock greater than 20 MHz, the duty cycle is corrected to 50%.

Figure 14. Acquisition Timing Diagram with Sample Clock Sources Other than STROBE



$$\begin{split} t_{\text{DDCSC}} &: \text{Time Delay from DDC Connector or to Internal Sample Clock} \\ -1 &\leq \delta_A \leq 2 : \text{Pattern Acquisition Channel Data Delay (Fraction of t_P)} \\ t_P &= \frac{1}{f} = \text{Period of Sample Clock} \\ t_{\text{SUSC}} &= \text{Set-Up Time to Sample Clock} \end{split}$$

ISUSC - Sel-Op Time to Sample Gloc

 t_{HSC} = Hold Time to Sample Clock

 $\delta_{\text{D}}=\text{Pattern}$ Acquisition Channel Deskew (Time)

CLK IN (SMA Jack Connector)

Specification	Value				Comments
Direction	Input into device				
Destinations	 Reference Sample c 		ne phase lock l	oop (PLL)	_
Input coupling	AC				—
Input protection	±10 VDC				Nominal.
Input impedance	50 Ω (defaul	t) or 1 kΩ			Software- selectable; Nominal.
Minimum detectable pulse width	2 ns	ns			
Clock requirements	Clock must l	be continuous a	and free-runnii	ıg.	
Clock ranges		Squar	e Waves		Nominal.
	Voltage range	300 mV _{pp} to	5.5 V _{pp}		3 dB cutoff point at 125 MHz
	Frequency range	20 kHz to 20	00 MHz		when using 1 k Ω input impedance.
	Duty cycle range	40% to 60%			impedance.
		Sine	Waves		
	Minimum voltage	630 mV _{pp} 1.265 V _{pp} 2.53 V _{pp} (0 dBm) (6 dBm) (12 dBm)			
	Maximum voltage	5.5 V _{pp}			
	Minimum frequency	10 MHz	5 MHz	2.5 MHz	
	Maximum frequency	200 MHz			

PFI 5 as STROBE (DDC Connector)

Specification	Value	Comments
Direction	Input to device	_
Electrical characteristics	Refer to the <i>Digital Acquisition Channels (DIO <023>, PFI 1, PFI 2, PFI 4, and PFI 5)</i> specifications in the <i>Channel Specifications</i> section.	
Destinations	Sample clock (acquisition only)	—
STROBE frequency range	800 Hz to 200 MHz	
STROBE duty cycle range	40% to 60% for clock frequencies \ge 20 MHz 25% to 75% for clock frequencies < 20 MHz Note : STROBE duty cycle is corrected to 50% at frequencies \ge 20 MHz.	At the programmed voltage input high (V _{IH}) threshold.
Minimum detectable pulse width	2 ns	inconord.
Clock requirements	Clock must be continuous and free-running.	

PXIe_DStarA (PXI Express Backplane)

Specification	Value	Comments
Direction	Input to device	—
Destinations	 Reference clock—for the phase lock loop (PLL) Sample clock 	_
PXIe_DStarA frequency range	800 Hz to 200 MHz	—
PXIe_DStarA duty cycle range	40% to 60%	
Clock requirements	Clock must be continuous and free-running.	—

CLK OUT (SMA Jack Connector)

Specification	Va	lue	Comments
Direction	Output from device		
Sources	 Sample clock (excluding Reference clock (PLL) 	_	
Generation voltage level	Low Voltage Levels, Characteristic	Nominal.	
	0 V 3.3 V		
Drive strength	±33 mA		—
Output impedance	50 Ω	Nominal.	
Output protection	The device can indefinitely between 0 V and 5 V.	sustain a short to any voltage	

PFI 4 as DDC CLK OUT (DDC Connector)

Specification	Value	Comments
Direction	Output from device	—
Sources	Sample clock (generation only)	STROBE and acquisition Sample clock cannot be routed to DDC CLK OUT.
Electrical characteristics	Refer to the <i>Digital Generation Channels (DIO</i> <023>, <i>PFI 1, PFI 2, PFI 4, and PFI 5)</i> specifications in the <i>Channel Specifications</i> section.	

Reference Clock (PLL)

Specification	Value	Comments
Reference clock sources	 PXI_CLK100 (PXI Express backplane) CLK IN (SMA jack connector) PXIe_DStarA (PXI Express backplane) None (internal oscillator locked to an internal reference) 	Provides the reference frequency for the PLL.
Reference clock frequency range	5 MHz to 100 MHz (integer multiple of 1 MHz)	_
Reference clock frequency accuracy	< 5,000 ppm	Required accuracy of the external Reference clock source.
Lock time	\leq 25 ms	Not including software latency.
Reference clock duty cycle range	40% to 60%	_
Reference clock destinations	CLK OUT (SMA jack connector)	

Memory and Scripting

Specification	Valu	le	Comments
Memory architecture	The NI 6555/6556 uses the Synchronization and Memory Core (SMC) technology in which waveforms and instructions share onboard memory. Parameters such as number of script instructions, maximum number of waveforms in memory, and number of samples available for waveform storage are flexible and user-defined.		Refer to the Onboard Memory section in the NI Digital Waveform Generator/ Analyzer Help for more information.
Onboard memory	NI 6555/NI 6556	NI 6556 Only	Maximum limit
size (generation)	8 Mbit/channel	64 Mbit/channel	for generation sessions assumes no scripting instructions.
Onboard memory size (acquisition)	8 Mbit/channel 64 Mbit/channel		—
Generation modes	Single-waveform mode : Generate a single wavefor continuously.	rm once, <i>n</i> times, or	
	Scripted mode: Generate a simple or complex sequence of waveforms. Use scripts to describe the waveforms to be generated, the order in which the waveforms are generated, how many times the waveforms are generated, and how the device responds to Script triggers.		

Specification	Value				Comments
Generation		Sample Rate		Sample rate	
minimum waveform size in	Configuration	200	MHz	100 MHz	dependent. Increasing
samples (S)	Single waveform	1	S	1 S	sample rate increases minimum
	Continuous waveform	12	8 S	64 S	waveform size requirement. For
	Stepped sequence	12	8 S	64 S	more information about these
	Burst sequence	1056 S		512 S	configurations, refer to the <i>Common</i> <i>Scripting Use</i> <i>Cases</i> topic in the <i>NI Digital</i> <i>Waveform</i> <i>Generator/</i> <i>Analyzer Help.</i>
Generation finite repeat count	1 to 16,777,216				_
Generation			Regardless of		
waveform quantum	1 sample		2	2 samples	waveform size, NI-HSDIO
Generation	Data width =	= 4	Dat	a width = 2	allocates waveforms in
waveform block size (in physical memory)	32 samples	64 samples		4 samples	blocks of physical memory.
Acquisition minimum record size	1 sample		Regardless of waveform size, NI-HSDIO allocates at least 640 bytes for a record.		
Acquisition record quantum	1 sample				_

Specification	Value	Comments
Acquisition maximum number of records	2,147,483,647	Session should fetch fast enough so that unfetched data is not overwritten.
Acquisition number of pre-Reference trigger samples	0 up to full record	_
Acquisition number of post-Reference trigger samples	0 up to full record	_
Hardware compare error FIFO depth	4,094	
Hardware compare number of unique enable states	255	_
Hardware compare maximum speed	200 MHz	

Triggers (Inputs to the NI 6556)

Specification	Value	Comments
Trigger types	 Start trigger Pause trigger Script trigger <03> (generation sessions only) Reference trigger (acquisition sessions only) Advance trigger (acquisition sessions only) Stop Trigger (generation sessions only) 	—
Sources	 PFI 0 (SMA jack connector) PFI <13> (DDC connector) PFI <2431> (DDC connector) PXI_TRIG<07> (PXI Express backplane) Pattern match (acquisition sessions only) Software (user function call) Disabled (do not wait for a trigger) 	
Trigger detection	 Start trigger (edge detection: rising or falling) Pause trigger (level detection: high or low) Script trigger <03> (edge detection: rising or falling; level detection: high or low) Reference trigger (edge detection: rising or falling) Advance trigger (edge detection: rising or falling) Stop Trigger (edge detection: rising or falling) 	_
Minimum required trigger pulse width	15 ns	Typical. Only applies to Digital Edge Triggers.
Destinations	 PFI 0 (SMA jack connectors) PFI <13> (DDC connector) PFI <2431> (DDC connector) PXI_TRIG<06> (PXI Express backplane) 	Each trigger can be routed to any destination except the Pause trigger. The Pause trigger cannot be exported.

Specification		Va	lue		Comments
Trigger rearm time	Start to Reference Trigger	Start to Advance Trigger	Advance to Advance Trigger	Reference to Reference Trigger	Maximum number of samples.
	150 S	220 S	220 S	220 S	
Delay from	Generatior	n Sessions	Acquisitio	n Sessions	Maximum;
Pause trigger to Pause state and Stop trigger to Done state	55 Sample Cla 300 ns	ock periods +	Synchronous data.	with the	Use the Data Active event during generation to determine on a sample by sample basis when the device enters the Pause or Done states.
Delay from trigger to digital data output	6 Sample Clo	ck periods + 6	00 ns		Maximum; Start trigger and Script triggers.

Events (Generated from the NI 6556)

Specification	Value	Comments
Event type	 Marker <02> (generation sessions only) Data Active event (generation sessions only) Ready for Start event Ready for Advance event (acquisition sessions only) End of Record event (acquisition sessions only) 	_

Specification	Value	Comments
Destinations	 PFI 0 (SMA jack connectors) PFI <13> (DDC connector) PFI <2431> (DDC connector) PXI_TRIG<06> (PXI Express backplane) 	Each event can be routed to any destination, except the Data Active event. The Data Active event can only be routed to the PFI channels.
Marker time resolution (placement)	Markers can be placed at any sample.	—

Miscellaneous

Specification	Value	Comments
Warm-up time	30 minutes	From driver loaded.
External calibration interval	1 year	

Power

Specification	12 V	3.3 V	Total Power	Comments
Maximum allowed current	5.2 A	5.7 A	—	Maximum allowed power before device
Maximum allowed device power		_	76 W	shut down requiring reset of the device.

Specification	12 V	3.3 V	Total Power	Comments
3.3 V swing at 200 Mbps	4.5 A	4.1 A	67.5 W	Typical results are commensurate with an aggressive user application using all data channels into a high-impedance load with active loads disabled
5.0 V swing at 100 Mbps	4.3 A	4.0 A	64.8 W	
8.0 V swing at 50 Mbps	4.3 A	3.8 A	64.1 W	
3.3 V swing at 100 Mbps with Active Load set to 24 mA	4.7 A	4.5 A	71.5 W	(unless otherwise noted) across temperature.

Physical

Specification	Value	Comments
Dimensions	$21.6 \times 2.0 \times 13.0$ cm	
	Dual 3U CompactPCI Express slot; PXI Express compatible	
Weight	28 oz (793 g)	—

I/O Panel Connectors

Label	Function(s)	Connector Type
CLK IN	External Sample clock, external Reference clock.	SMA jack
PFI 0	Events, triggers.	SMA jack
CLK OUT	External Sample clock, exported Reference clock.	SMA jack
AUX I/O	External force, external sense, and analog calibration. Note : Supported on the NI 6556 only.	Combicon
Digital Data & Control (DDC)	Digital data channels, PPMU channels, exported Sample clock, STROBE, events, triggers.	68-pin VHDCI
REMOTE SENSE	PPMU remote sensing channels, external force, external sense, and analog calibration.	68-pin VHDCI

Software

Specification	Value	Comments
Driver software	NI-HSDIO driver software 1.8.1 or later for the NI 6556; NI-HSDIO 1.9 for the NI 6555. NI-HSDIO allows you to configure and control the NI 6555/6556. NI-HSDIO provides application interfaces for many development environments. NI-HSDIO follows IVI application programming interface (API) guidelines.	_
Application software	 NI-HSDIO provides programming interfaces for the following application development environments (ADEs): National Instruments LabVIEW National Instruments LabWindows[™]/CVI[™] Microsoft Visual C/C++ 	Refer to the <i>NI-HSDIO</i> <i>Readme</i> for more information about supported ADE versions.
Test panel	National Instruments Measurement & Automation Explorer (MAX) provides test panels with basic acquisition and generation functionality for the NI 6555/6556. MAX is included on the NI-HSDIO driver media.	

Environment

E

Note To ensure that the NI 6555/6556 cools effectively, follow the guidelines in the *Maintain Forced Air Cooling Note to Users* included with the NI 6555/6556. The NI 6555/6556 is intended for indoor use only.

Specification	Value	Comments
Operating temperature	0 to +45 °C in all NI PXI Express and hybrid NI PXI Express chassis. (Meets IEC 60068-2-2.)	—
Operating relative humidity	10% to 90% relative humidity, noncondensing (Meets IEC 60068-2-56.)	
Altitude	2,000 m at 25 °C ambient temperature	—
Pollution Degree	2	

Specification	Value	Comments
Storage temperature	-20 to +70 °C (Meets IEC-60068-2-2.)	_
Storage relative humidity	5% to 95% relative humidity, noncondensing (Meets IEC 60068-2-56.)	
Operating shock	30 g, half-sine, 11 ms pulse (Meets IEC 60068-2-27. Test profile developed in accordance with MIL-PRF-28800F.)	
Storage shock	50 g, half-sine, 11 ms pulse (Meets IEC 60068-2-27. Test profile developed in accordance with MIL-PRF-28800F.)	
Operating vibration	5 Hz to 500 Hz, 0.3 g _{rms} (Meets IEC 60068-2-64.)	_
Storage vibration	5 Hz to 500 Hz, 2.46 g _{rms} (Meets IEC 60068-2-64. Test profile exceeds requirements of MIL-PRF-28800F, Class B.)	

Safety



Caution The protection provided by the NI PXIe-6555/6556 can be impaired if it is used in a manner not described in this document.

This product meets the requirements of the following standards of safety for electrical equipment for measurement, control, and laboratory use:

- IEC 61010-1, EN 61010-1
- UL 61010-1, CSA 61010-1



Note For UL and other safety certifications, refer to the product label or the *Online Product Certification* section.

Electromagnetic Compatibility

This product meets the requirements of the following EMC standards for electrical equipment for measurement, control, and laboratory use:

- EN 61326-1 (IEC 61326-1): Class A emissions; Basic immunity
- EN 55011 (CISPR 11): Group 1, Class A emissions
- AS/NZS CISPR 11: Group 1, Class A emissions
- FCC 47 CFR Part 15B: Class A emissions
- ICES-001: Class A emissions



Note In the United States (per FCC 47 CFR), Class A equipment is intended for use in commercial, light-industrial, and heavy-industrial locations. In Europe, Canada, Australia, and New Zealand (per CISPR 11) Class A equipment is intended for use only in heavy-industrial locations.



Note Group 1 equipment (per CISPR 11) is any individual, scientific, or medical equipment that does not intentionally generate radio frequency energy for the treatment of material or inspection/analysis purposes.



Note For EMC declarations and certifications, refer to the *Online Product Certification* section of this document.

CE Compliance (6

This product meets the essential requirements of applicable European Directives as follows:

- 2006/95/EC; Low-Voltage Directive (safety)
- 2004/108/EC; Electromagnetic Compatibility Directive (EMC)

Online Product Certification

To obtain product certifications and the Declaration of Conformity for this product, visit ni.com/certification, search by model number or product line, and click the appropriate link in the Certification column.

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